### **Absolute Maximum Ratings**

Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Electrical specifications do not apply when operating the device beyond its specified **Operating Ratings**.

Power Dissipation	Internally Limited
Lead Temperature (Soldering, 5 seconds)	
Operating Junction Temperature Range	–40°C to +125°C
Input Supply Voltage	–20V to +60V
ENABLE Input Voltage	–20V to +60V
SO-8 θ <sub>JA</sub>	See Note 1

# **Recommended Operating Conditions**

Input Voltage	2.5V to 26V
Operating Junction Temperature Range	. –40°C to +125°C
ENABLE Input Voltage	0V to V <sub>IN</sub>

## **Electrical Characteristics**

Limits in standard typeface are for  $T_J = 25^{\circ}$ C and limits in **boldface** apply over the junction temperature range of -40°C to +125°C. Specifications are for each half of the (dual) MIC5202. Unless otherwise specified,  $V_{IN} = V_{OUT} + 1V$ ,  $I_L = 1$ mA,  $C_L = 10\mu$ F, and  $V_{CONTROL} \ge 2.0V$ .

Symbol	Parameter	Condition	Min	Тур	Max	Units
V <sub>o</sub>	Output Voltage	Variation from specified V <sub>out</sub> Accuracy	-1 -2		1 2	%
ΔV <sub>o</sub> ppm/°C	Output Voltage	(Note 2)		40	150	
ΔΤ	Temperature Coef.					
$\frac{\Delta V_{o}}{V_{o}}$	Line Regulation	$V_{IN} = V_{OUT} + 1 V \text{ to } 26V$		0.004	0.10 <b>0.40</b>	%
$\frac{\Delta V_{o}}{V_{o}}$	Load Regulation	I <sub>L</sub> = 0.1mA to 100mA (Note 3)		0.04	0.16 <b>0.30</b>	%
V <sub>IN</sub> – V <sub>O</sub>	Dropout Voltage (Note 4)	$I_{L} = 100\mu A$ $I_{L} = 20m A$ $I_{L} = 30m A$ $I_{L} = 50m A$ $I_{L} = 100m A$		17 130 150 180 225	350	mV
I <sub>Q</sub>	Quiescent Current	$V_{CONTROL} \le 0.7V$ (Shutdown)		0.01		μA
I <sub>GND</sub>	Ground Pin Current	$V_{CONTROL} \ge 2.0V, I_{L} = 100\mu A$ $I_{L} = 20m A$ $I_{L} = 30m A$ $I_{L} = 50m A$ $I_{L} = 100m A$		170 270 330 500 1200	1500	μA
PSRR	Ripple Rejection			75		dB
	Ground Pin Current at Dropout	$V_{IN} = 0.5V$ less specified $V_{OUT}$ , $I_{L} = 100\mu$ A (Note 5)		270	330	μA
ILIMIT	Current Limit	V <sub>OUT</sub> = 0V		280		mA
ΔV <sub>0</sub> ΔP <sub>D</sub>	Thermal Regulation	(Note 6)		0.05		%/W
e <sub>n</sub>	Output Noise			100		μV

### **Control Input**

V <sub>IL</sub>	Input Voltage Level Logic Low Logic High	OFF ON	2.0		0.7	V
I <sub>IL</sub> IH	Control Input Current	$V_{IL} \le 0.7V$ $V_{IH} \ge 2.0V$		0.01 8	50	μA

Note 1:	Absolute maximum ratings indicate limits beyond which damage to the component may occur. Electrical specifications do not apply when operating the device outside of its rated operating conditions. The maximum allowable power dissipation is a function of the maximum junction temperature, $T_{J(MAX)}$ the junction-to-ambient thermal resistance, $\theta_{JA}$ , and the ambient temperature, $T_{A}$ . The maximum allowable power dissipation at any ambient temperature is calculated using: $P_{(MAX)} = (T_{J(MAX)} - T_{A}) / \theta_{JA}$ . Exceeding the maximum allowable power dissipation will result in excessive die temperature, and the regulator will go into thermal shutdown. The junction to ambient thermal resistance of the MIC5202BM is 160°C/W mounted on a PC board.
Note 2:	Output voltage temperature coefficient is defined as the worst case voltage change divided by the total temperature range.
Note 3:	Regulation is measured at constant junction temperature using low duty cycle pulse testing. Parts are tested for load regula- tion in the load range from 0.1mA to 100mA. Changes in output voltage due to heating effects are covered by the thermal regulation specification.
Note 4:	Dropout Voltage is defined as the input to output differential at which the output voltage drops 2% below its nominal value measured at 1V differential.
Note 5:	Ground pin current is the regulator quiescent current plus pass transistor base current. The total current drawn from the supply is the sum of the load current plus the ground pin current.
Note 6:	Thermal regulation is defined as the change in output voltage at a time t after a change in power dissipation is applied, excluding load or line regulation effects. Specifications are for a 100mA load pulse at $V_{IN}$ = 26V for t = 10ms, and is measured

## Typical Characteristics (Each Regulator—2 Regulators/Package)



















## **Applications Information**

#### **External Capacitors**

A1µF capacitor is recommended between the MIC5202 output and ground to prevent oscillations due to instability. Larger values serve to improve the regulator's transient response. Most types of tantalum or aluminum electrolytics will be adequate; film types will work, but are costly and therefore not recommended. Many aluminum electrolytics have electrolytes that freeze at about –30°C, so solid tantalums are recommended for operation below –25°C. The important parameters of the capacitor are an effective series resistance of about 5 $\Omega$  or less and a resonant frequency above 500kHz. The value of this capacitor may be increased without limit.

At lower values of output current, less output capacitance is required for output stability. The capacitor can be reduced to  $0.47\mu$ F for current below 10mA or  $0.33\mu$ F for currents below 1 mA. A 1 $\mu$ F capacitor should be placed from the MIC5202 input to ground if there is more than 10 inches of wire between the input and the AC filter capacitor or if a battery is used as the supply.

#### **ENABLE Input**

The MIC5202 features nearly zero OFF mode current. When the ENABLE input is held below 0.7V, all internal circuitry is powered off. Pulling this pin high (over 2.0V) re-enables the device and allows operation. The ENABLE pin requires a small amount of current, typically 15µA. While the logic threshold is TTL/CMOS compatible, ENABLE may be pulled as high as 30V, independent of the voltage on  $V_{IN}$ . The two portions of the MIC5202 may be enabled separately.

#### **General Notes**

The MIC5202 will remain stable and in regulation with no load in addition to the internal voltage divider, unlike many other voltage regulators. This is especially important in CMOS RAM keep-alive applications. Thermal shutdown is independant on both halfs of the dual MIC5202, however an over-temperature condition on one half might affect the other because of proximity. When used in dual supply systems where the regulator load is returned to a negative supply, the output voltage must be diode clamped to ground.

Both MIC5202 GROUND pins must be tied to the same ground potential. Isolation between the two halfs allows connecting the two  $V_{IN}$  pins to different supplies.

### Thermal Considerations Part I. Layout

The MIC5202-xxBM (8-pin surface mount package) has the following thermal characteristics when mounted on a single layer copper-clad printed circuit board.

PC Board Dielectric	$\theta_{JA}$
FR4	160°C/W
Ceramic	120°C/W

Multi-layer boards having a ground plane, wide traces near the pads, and large supply bus lines provide better thermal conductivity.

The "worst case" value of 160°C/W assumes no ground plane, minimum trace widths, and a FR4 material board.

#### Part II. Nominal Power Dissipation and Die Temperature

The MIC5202-xxBM at a 25°C ambient temperature will operate reliably at up to 625mW power dissipation when mounted in the "worst case" manner described above. At an ambient temperature of 55°C, the device may safely dissipate 440mW. These power levels are equivalent to a die temperature of 125°C, the recommended maximum temperature for nonmilitary grade silicon integrated circuits.



Minimum recommended board pad size, SO-8.

# **Package Information**



8-Pin SOP (M)

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